



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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PRODUCT DESCRIPTION

Laird Tflex™ HD700 is our latest product in our High Deflection series. Tflex™ HD700 combines 5 W/mK thermal conductivity with superior pressure versus deflection characteristics. The combination will allow minimal stress on components while also yielding low thermal resistance. As a result, less mechanical and thermal stresses will be experienced within your device.

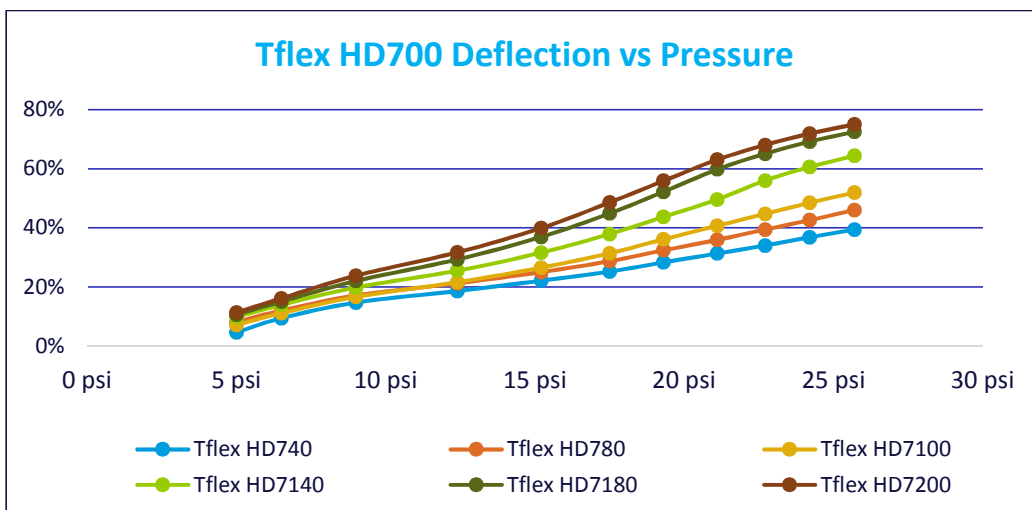
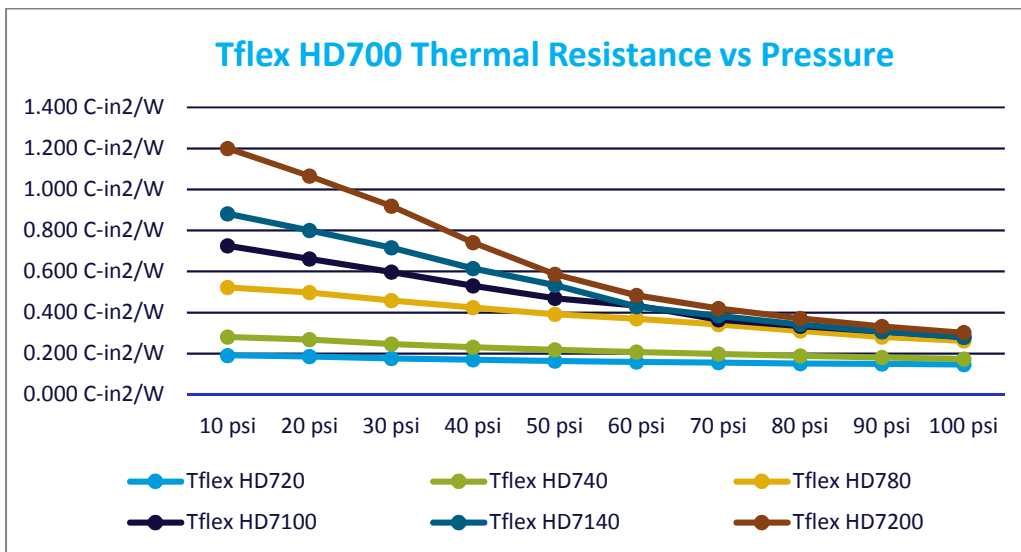
Tflex™ HD700 is available in thickness from 0.5mm (0.020”) to 5mm (0.200”). Laird can provide material to meet your production needs in any region through our local production facilities. Please contact your local Laird sales or field engineering contact for samples or questions.

FEATURES AND BENEFITS

- 5.0 W/mK thermal conductivity
- Low pressure versus deflection
- Excellent surface wetting for low contact resistance
- Minimizes board and component stress
- Large tolerance applications
- Environmentally friendly solution that meets regulatory requirements including RoHS and REACH

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Ceramic filled silicone sheet	N/A
Color	Pink	Visual
Thickness Range	0.50mm (0.020”) 5.0mm (0.200”)	N/A
Thermal Conductivity (W/mK)	5.0	ASTM D5470
Density (g/cc)	3.3	Helium Pycnometer
Hardness (Shore 00)	66 (0.5-0.75mm) 55 (1-5mm)	ASTM D2240
Outgassing TML (weight %)	0.23	ASTM E595
Outgassing CVCM (weight %)	0.07	ASTM E595
Temperature Range	-50°C to 200°C	Laird Test Method
Rth@ 40 mils, 10 psi	0.287°C-in2/W	ASTM D5470 (Modified)
Dielectric Constant @ 1 MHz	5.01	ASTM D150
UL Flammability Rating	V-0	UL 94
Volume Resistivity	1.4x 10 ¹⁴ ohm-cm	ASTM D257



AVAILABILITY

STANDARD THICKNESSES

- 0.5mm (0.020”) to 5.0mm (0.200”) thick material available in 0.25mm (0.010”) increments
- Available in standard sheet sizes of 18” x 18” and 9” x 9” or custom die cut parts

OPTIONS

- DC1 – eliminate tack from one side

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. HD7xxx indicates Tflex HD700 product line with thickness in mils (0.001”)

EXAMPLES:

- Tflex™ HD740 = 0.040” thick Tflex™ HD700 material
- Tflex™ HD7100,DC1 = 0.10” thick Tflex™ HD700 material with DC1 option

A17758-00 Tflex HD700 DS 071017